

DATA SHEET

TDA8601 RGB/YUV and fast blanking switch

Product specification
Supersedes data of July 1994
File under Integrated Circuits, IC02

1996 Jun 27

RGB/YUV and fast blanking switch

TDA8601

FEATURES

- YUV/RGB and fast blanking switch
- 3-state output
- Selectable clamp:
 - passive (with diodes) or
 - active clamp
- Bandwidth greater than 22 MHz
- Fully ESD protected
- Latch-up free.

APPLICATIONS

- Standard and high definition television sets
- Peri-television sets.

GENERAL DESCRIPTION

The device is intended for switching between two RGB or YUV video sources. The outputs can be set to a high-impedance state to enable parallel connection of several devices.

A HIGH level on SEL (pin 5) selects the video inputs of Channel 2. The IOCNTN control pin (pin 16) defines the 3-state outputs and clamp inputs:

- HIGH = 3-state outputs (also for test; active clamp)
- LOW = passive clamp at the video inputs (diode)
- Sandcastle: the video signal is clamped with an active clamp during the sync pulse.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_P	supply voltage		7.2	8.0	8.8	V
G_V	voltage gain		−0.5	0	+0.5	dB
B	bandwidth	at 3 dB	22	–	–	MHz
α_{ct}	crosstalk attenuation between two video channels	$f_i = 5$ MHz	−60	–	–	dB
T_{amb}	operating ambient temperature		0	–	70	°C

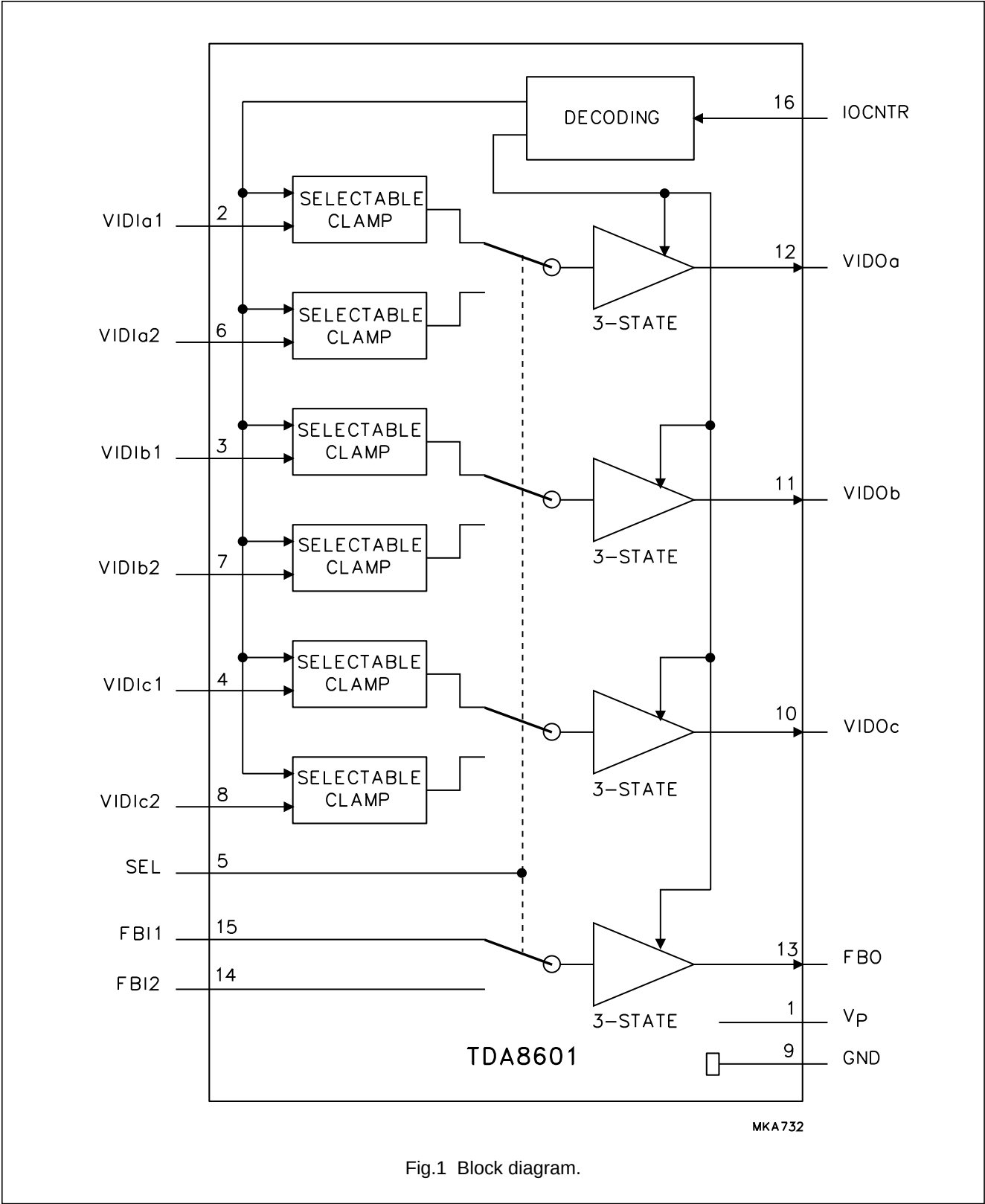
ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA8601	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1
TDA8601T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

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BLOCK DIAGRAM

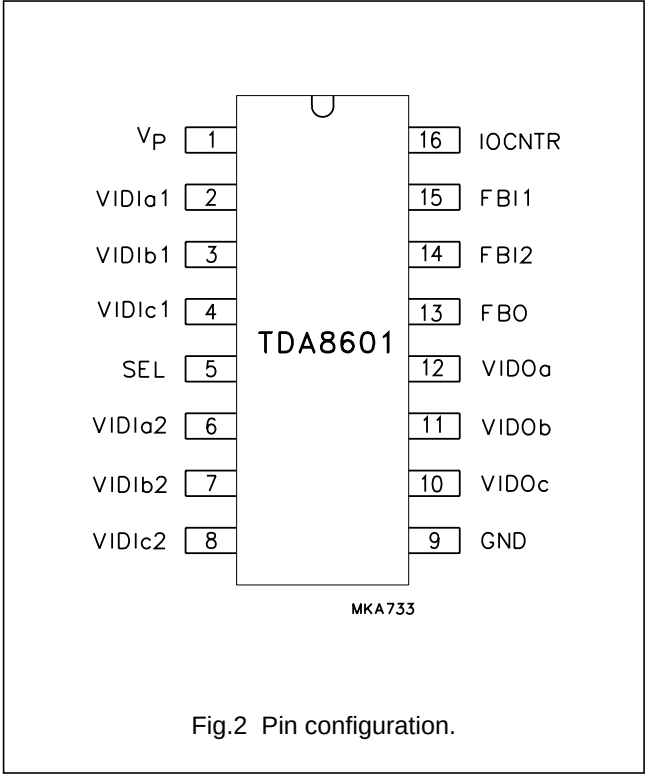


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PINNING

SYMBOL	PIN	DESCRIPTION
V _P	1	supply voltage (8 V)
VIDIa1	2	video input a (channel 1)
VIDIb1	3	video input b (channel 1)
VIDIc1	4	video input c (channel 1)
SEL	5	channel selection
VIDIa2	6	video input a (channel 2)
VIDIb2	7	video input b (channel 2)
VIDIc2	8	video input c (channel 2)
GND	9	ground
VIDOc	10	video output c
VIDOb	11	video output b
VIDOa	12	video output a
FBO	13	fast blanking output signal
FBI2	14	fast blanking input signal (channel 2)
FBI1	15	fast blanking input signal (channel 1)
IOCNTNTR	16	control of video input or video output



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _P	supply voltage	−0.3	+12	V
V _i	input voltage (pins 2 to 4 and 6 to 8) referenced to ground	0	8.8	V
T _j	junction temperature	−	150	°C
T _{stg}	IC storage temperature	−55	+150	°C

HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices.

ESD in accordance with “MIL STD 883C” - “Method 3015”:

- Human body model: 1500 Ω, 100 pF, 3 pulses positive and 3 pulses negative on each pin with respect to ground. Class 2: 2000 to 3999 V.
- Machine model: 0 Ω, 200 pF, 3 pulses positive and 3 pulses negative on each pin with respect to ground. The IC withstands 200 V.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient in free air		
	DIP16	70	K/W
	SO16	115	K/W

OPERATING CHARACTERISTICS

The operating characteristics are the conditions within the IC when it is functional; these conditions can have any value. For example, condition V_{IL} (pin 5) is fixed at 0.5 V. The IC will then operate over the full temperature range and supply voltage range.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V _P	supply voltage		7.2	8.0	8.8	V
Video inputs (pins 1 to 3 and 6 to 8)						
V _{i(p-p)}	input video signal amplitude (peak-to-peak value)	R, G, B signals	–	0.7	1	V
		Y signal; active clamp	–	1	1.4	V
		–(B – Y) signal; active clamp	–	1.05	1.5	V
		–(R – Y) signal; active clamp	–	1.33	1.9	V
C _i	input clamp capacitor		–	47	–	nF
Control inputs (pins 5 and 16)						
V _{IH}	HIGH level input voltage (pin 5)	I _{IH} = 10 μA	0.9	–	V _P	V
V _{IL}	LOW level input voltage (pin 5)	I _{IL} = –10 μA	–	–	0.5	V
V _{IH}	HIGH level input voltage (pin 16)	I _{IH} = 10 μA	2.0	–	V _P	V
V _{IL}	LOW level input voltage (pin 16)	I _{IL} = –10 μA	–	–	0.8	V
V _{sc}	sandcastle input voltage level (pin 16)	zero level	–	–	1.1	V
		blanking level	2.0	–	3.1	V
		clamp level	3.9	–	5.5	V
t _w	clamp pulse width	SECAM mode	–	3.6	–	μs
		PAL mode	–	2.5	–	μs
Fast blanking inputs (pins 14 and 15)						
V _{IH}	HIGH level input voltage		0.95	–	V _P	V
V _{IL}	LOW level input voltage		–	–	0.5	V
Video outputs (pins 10 to 12)						
C _L	output load capacitor		–	40	100	pF
R _L	output load resistor	note 1	1	–	–	kΩ

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Fast blanking output (pin 13)						
C_L	output load capacitor		–	40	100	pF
R_L	output load resistor	note 1	1	–	–	k Ω

Note

- For the DIP16 package, the thermal resistance is lower. The minimum value for the output load resistor is 270 Ω .

CHARACTERISTICS

The typical values are given for $V_P = 8$ V; $T_{amb} = 25$ °C. $C_L = 40$ pF; no load resistor; measured in application circuit of Fig.8 over full supply voltage and temperature range; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
I _P	supply current	no resistive load on the outputs	–	33	40	mA
SVRR	supply voltage rejection ratio	f _i = 40 Hz to 50 kHz; note 1	–	–	–36	dB
		f _i = 40 Hz; note 1	–	–51	–36	dB
Video inputs (pins 1 to 3 and 4 to 6)						
R _i	input resistance	for each type of clamp	10	–	–	kΩ
C _{i(max)}	maximum input capacitance		–	3	–	pF
V _{clamp}	input clamping voltage level	I _i = –50 mA; passive clamp	1.05	1.21	1.35	V
		I _i = 50 mA; active clamp; V _{IOCNT} R = 3.9 V	2.05	2.42	2.70	V
		I _i = –50 mA; active clamp; V _{IOCNT} R = 3.9 V	2.05	2.37	2.70	V
I _{sink}	input sink current	V _i = 2 V; passive clamp	0.5	1.6	3	μA
I _{clamp}	maximum absolute input clamping current	V _i = V _{clamp} + 0.5 V; active clamp	200	–	–	μA

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Video outputs (pins 10 to 12)						
R _o	output resistance		–	–	50	Ω
R _{oZ}	output resistance	3-state output	0.1	–	–	MΩ
C _{oZ(max)}	maximum output capacitance	3-state output	–	3	–	pF
G _v	voltage gain	f _i = 1 MHz	–0.5	0	+0.5	dB
B	bandwidth	at ±0.5 dB	5	–	–	MHz
		at ±1 dB	10	–	–	MHz
		at ±3 dB	22	40	–	MHz
α _{ct}	crosstalk attenuation between two video channels	f _i = 5 MHz; note 2	–60	–	–	dB
		f _i = 10 MHz; note 2	–50	–	–	dB
		f _i = 22 MHz; note 2	–40	–	–	dB
α _{off}	isolation of the 3-state configuration	f _i = 5 MHz; note 2	–60	–	–	dB
		f _i = 10 MHz; note 2	–50	–	–	dB
		f _i = 22 MHz; note 2	–40	–	–	dB
SR	slew rate		100	120	–	V/μs
ΔG _m	gain matching between two different signals of the same channel	f _i = 5 MHz	–	–	0.5	dB
V _{o(bl)}	output blanking level voltage		2.1	2.23	2.7	V
V _{os(bl)}	output blanking offset voltage	V _{i(ch1)} = 0.7 V (p-p) (white); V _{i(ch2)} = 0 V (p-p) (black); active clamp; note 3	–	–	5	mV
		V _{i(ch1)} = 0.7 V (p-p) (white); V _{i(ch2)} = 0 V (p-p) (black); passive clamp; note 3	–	–	15	mV
ΔV _{os(bl)}	matching of output blanking offset voltage	V _{i(ch1)} = 0.7 V (p-p) (white); V _{i(ch2)} = 0 V (p-p) (black); active clamp; note 3	–	–	5	mV
		V _{i(ch1)} = 0.7 V (p-p) (white); V _{i(ch2)} = 0 V (p-p) (black); passive clamp; note 3	–	–	5	mV
Fast blanking inputs (pins 14 and 15)						
Z _i	input impedance		10	–	–	kΩ
Fast blanking output (pin 13)						
V _{OH}	HIGH level output voltage		2	2.35	3	V
V _{OL}	LOW level output voltage		0	0.15	0.3	V
Z _o	output impedance		–	–	50	Ω
SEL input (pin 5)						
Z _i	input impedance		10	–	–	kΩ

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Timing						
$t_{dSEL;VID}$	delay time between SEL input and video output	note 4	–	12	20	ns
$t_{dSEL;FBO}$	delay time between SEL input and fast blanking output	note 5	–	15	40	ns
t_{SWVID}	switching time of video output	note 4	–	8.5	15	ns
t_{SWFBO}	switching time of fast blanking output	note 5	–	8.5	15	ns
t_{dFB}	fast blanking level delay between input and output	note 6	–	13	20	ns
t_{dVID}	video delay between input and output	note 7	–	4	20	ns
Δt_{dVID}	delay difference between two video signals at the output	note 7	–	0.5	10	ns
$\Delta t_{dFB;VID}$	delay difference between fast blanking level and video at the output	note 7	–	5	10	ns

Notes

1. The supply voltage rejection ratio is measured at the video outputs (pins 10 to 12) when a sine wave is applied on the power supply pin (pin 1); where: $V_{DC} = 8\text{ V}$; $V_i = 100\text{ mV}$ (p-p). This additional sine wave on the power supply pin is guaranteed not to cause extraneous oscillations on the video control and fast blanking signals.
2. The 6 video inputs will contain the same signal. The source impedance is $50\ \Omega$.
3. The blanking offset is the level difference between the two channels when they are selected separately and, also, on one video output. This value is measured on each video signal.
4. The delay between the SEL input and the video output together with the switching time of the video output is illustrated in Fig.3. The amplitude of the video signal is 1.9 V (p-p) when the clamp is active and 1.0 V (p-p) when the clamp is passive.
5. The delay between the SEL input and fast blanking output together with the switching time of fast blanking output is illustrated in Fig.4.
6. The fast blanking delay between input and output is illustrated in Fig.5.
7. The video delay between input and output and delay differences are illustrated in Fig.6. Inputs 1 and 2 are either fast blanking input plus a video signal or two video signals. The amplitude of the video signal is 0.5 V (p-p). The video signal levels ($i1$, $i2$, $o1$ and $o2$) are 50% of the video amplitude. The fast blanking signal levels ($i1$ and $o1$) are 0.95 V when the signal rises and 0.5 V when the signal falls.

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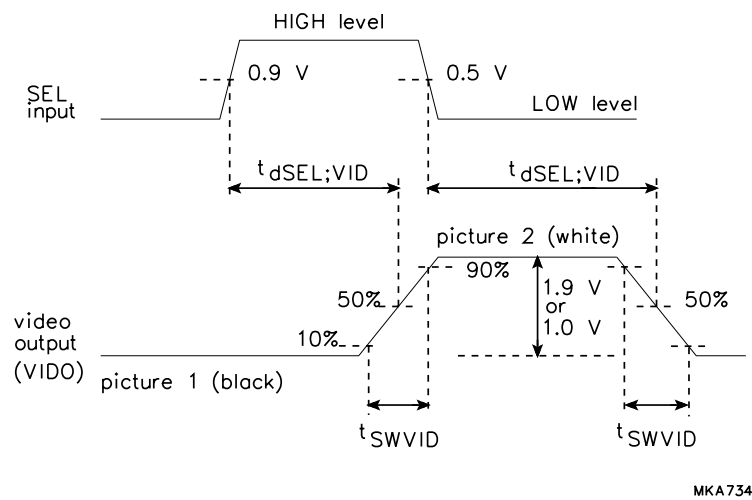


Fig.3 Timing definition: SEL and VIDO.

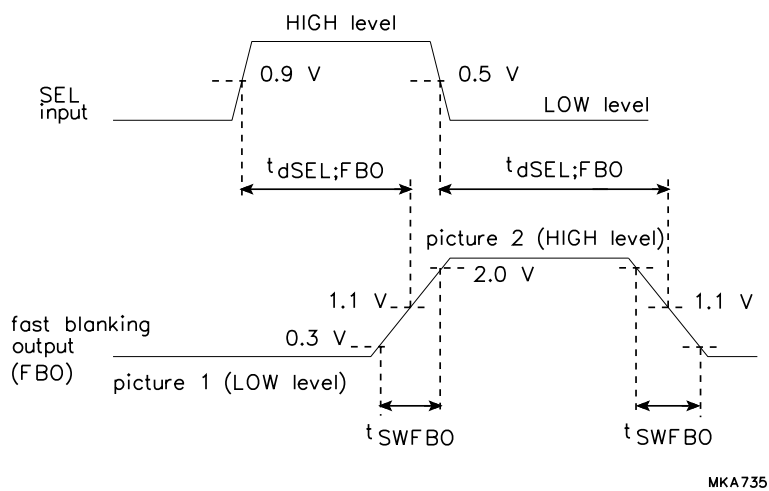


Fig.4 Timing definition: SEL and FBO.

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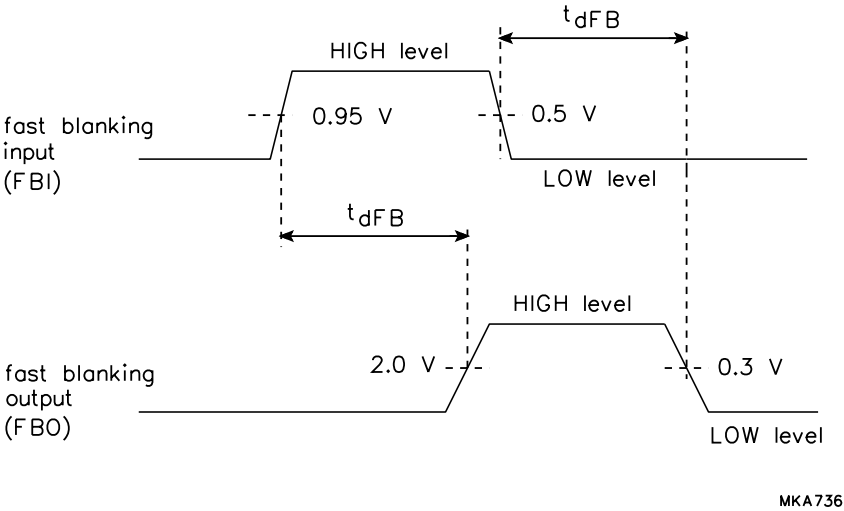


Fig.5 Timing definition: fast blanking delay.

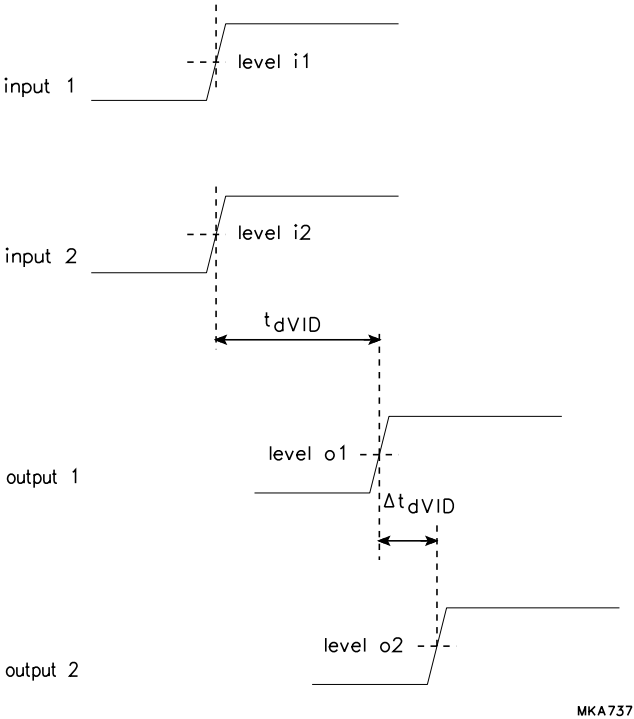


Fig.6 Timing definition: video delay.

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INTERNAL PIN CONFIGURATION

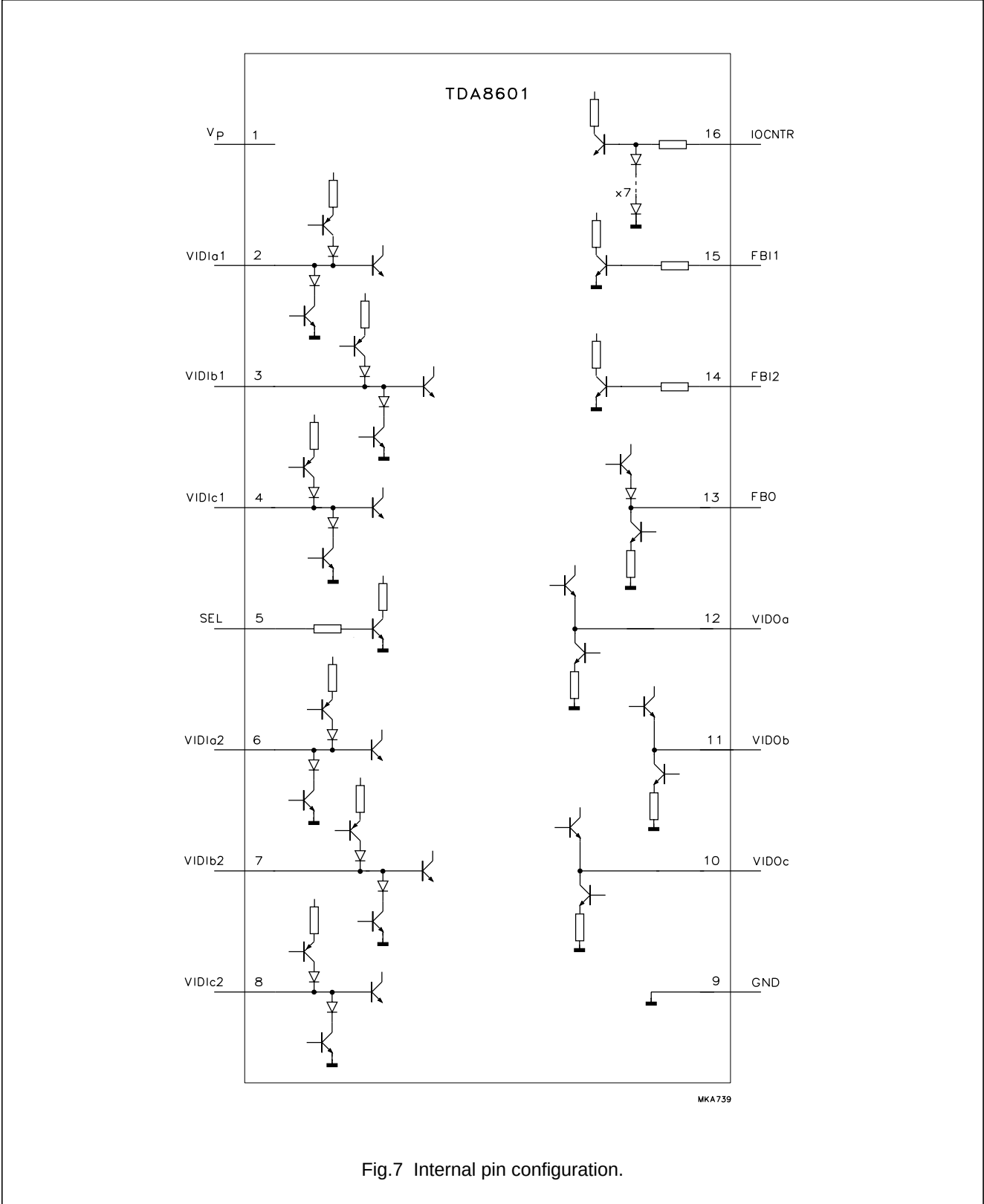


Fig.7 Internal pin configuration.

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APPLICATION INFORMATION

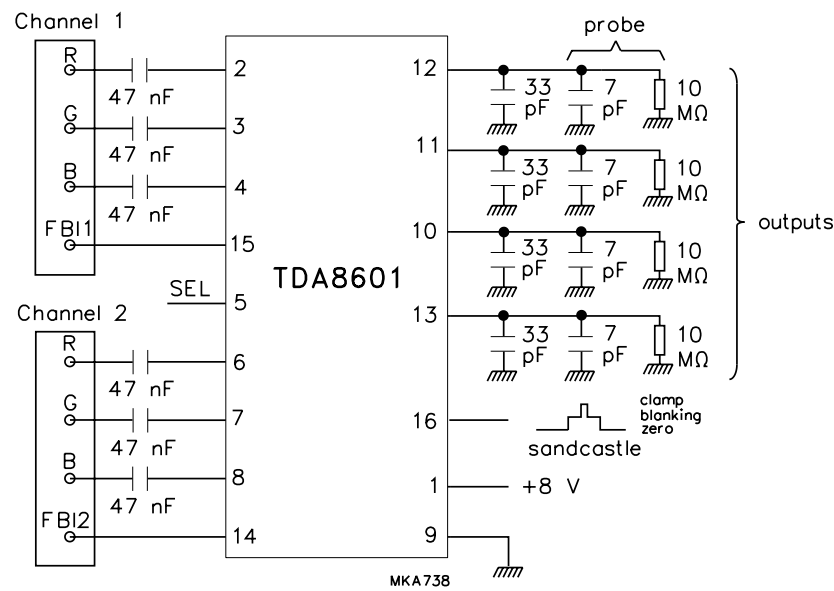


Fig.8 Application diagram.

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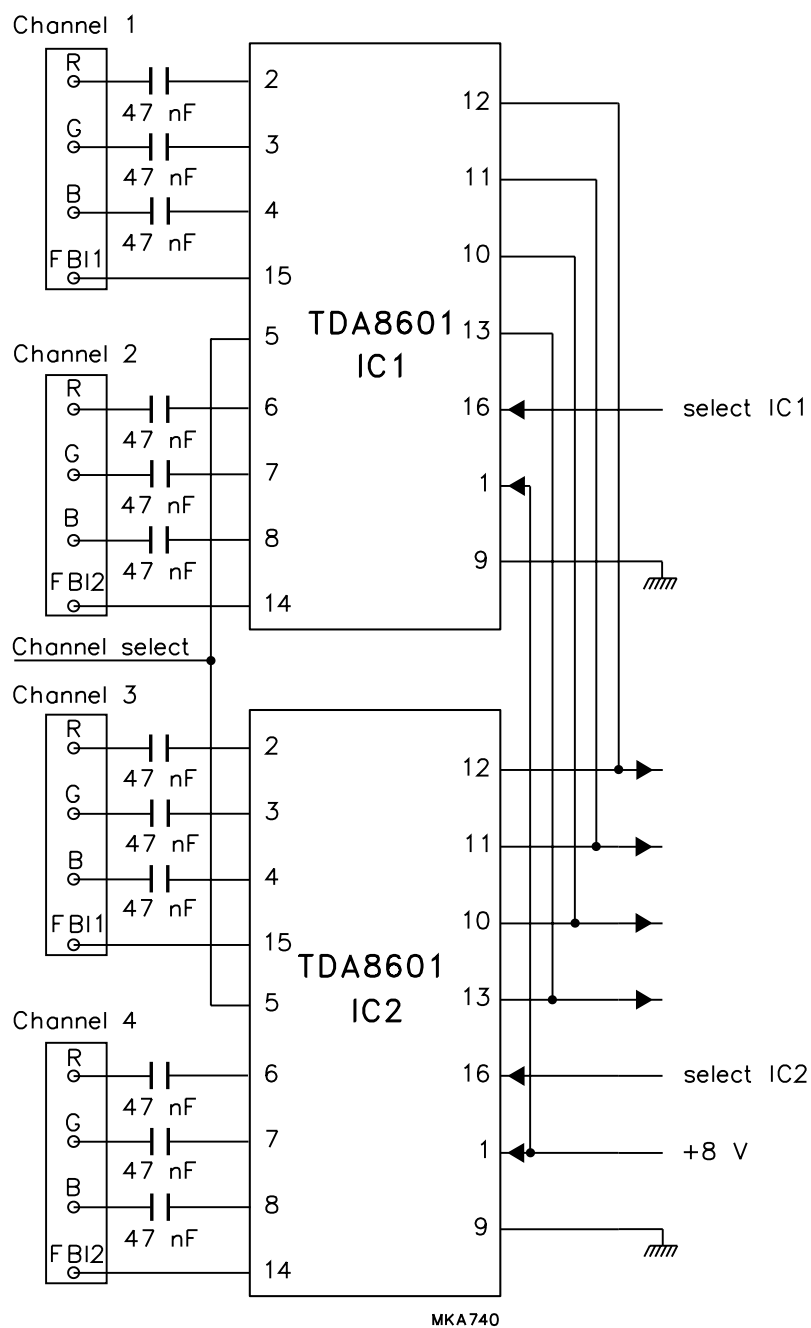


Fig.9 Schematic diagram of two TDA8601s operating four channels.

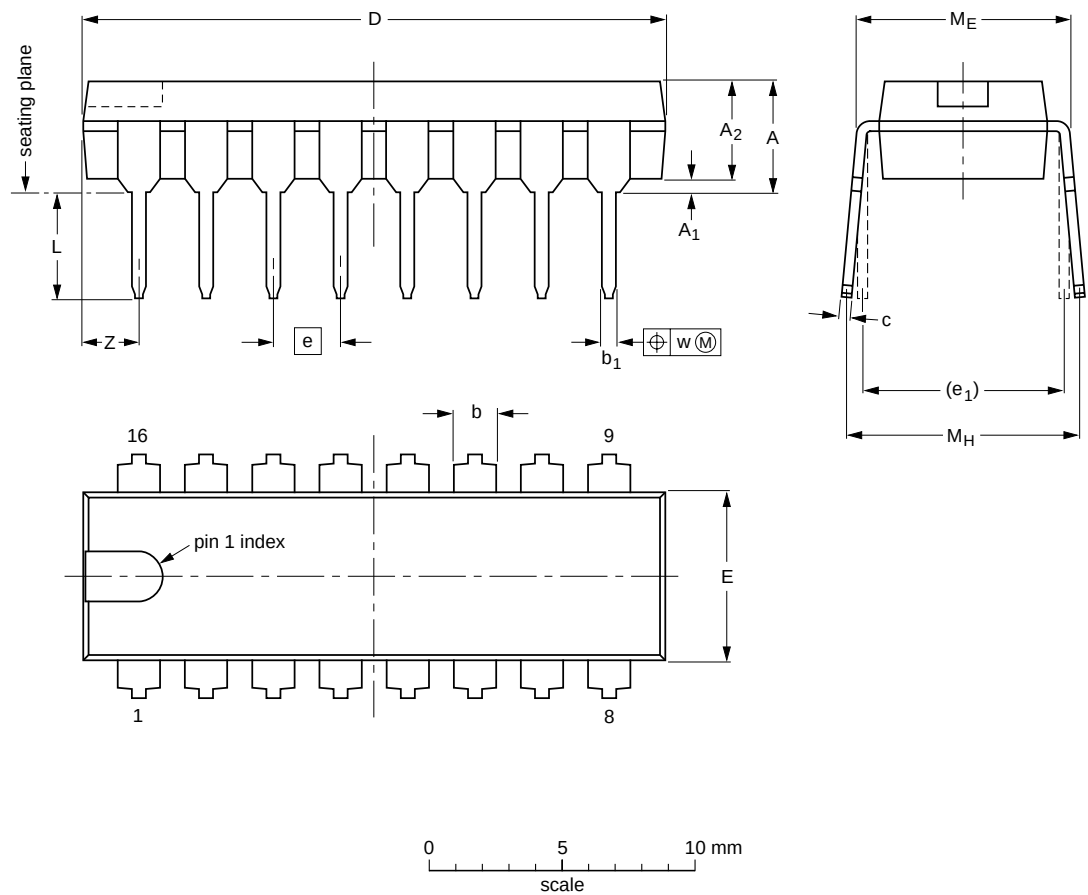
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PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1

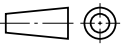


DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.020	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

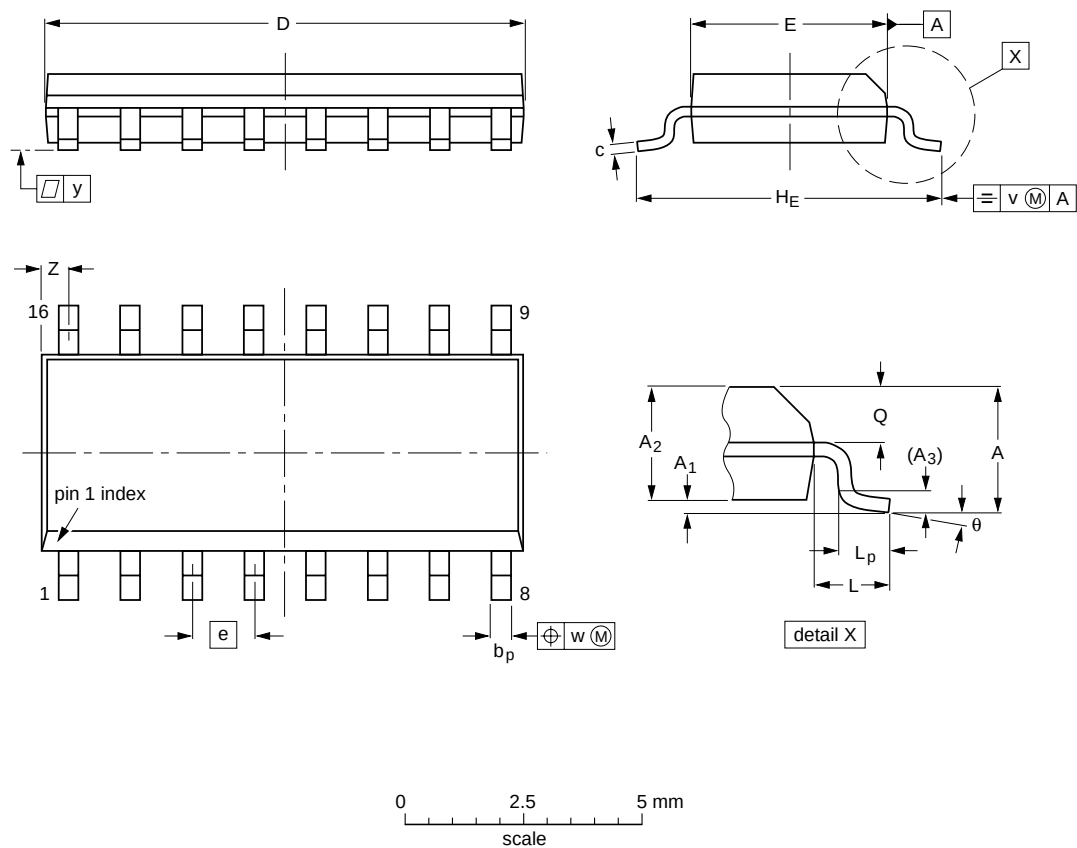
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-1	050G09	MO-001AE				92-10-02 95-01-19

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SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

SO

REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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NOTES

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NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113,
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoprojekt, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 689 211, Fax. +359 2 689 102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381, Fax. +1 708 296 8556

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,
Tel. +45 32 88 2636, Fax. +45 31 57 1949

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 615 800, Fax. +358 615 80920

France: 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex,
Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 23 52 60, Fax. +49 40 23 536 300

Greece: No. 15, 25th March Street, GR 17778 TAVROS,
Tel. +30 1 4894 339/911, Fax. +30 1 4814 240

Hungary: see Austria

India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd.
Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722

Indonesia: see Singapore

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180,
Tel. +972 3 645 0444, Fax. +972 3 648 1007

Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,
20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,
Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +1 800 234 7381, Fax. +1 708 296 8556

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 83749, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA,
Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 926 5361, Fax. +7 095 564 8323

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000,
Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Rua do Rocio 220, 5th floor, Suite 51,
04552-903 São Paulo, SÃO PAULO - SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 829 1849

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 3 301 6312, Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: PHILIPS TAIWAN Ltd., 23-30F, 66,
Chung Hsiao West Road, Sec. 1, P.O. Box 22978,
TAIPEI 100, Tel. +886 2 382 4443, Fax. +886 2 382 4444

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,
Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,
Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 2A Akademika Koroleva str., Office 165,
252148 KIEV, Tel. +380 44 476 0297/1642, Fax. +380 44 476 6991

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381, Fax. +1 708 296 8556

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 825 344, Fax. +381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications,
Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com/ps/>

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